

### RS1A THRU RS1M Fast Recovery Rectifier Diodes

#### Features

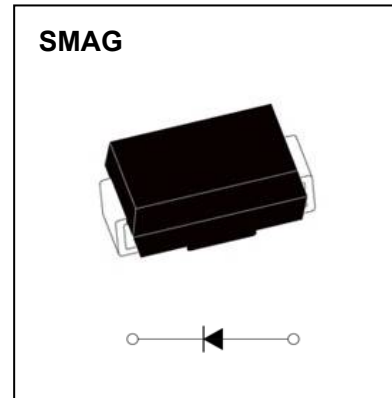
- $I_{F(AV)}$  1A
- $V_{RRM}$  50V-1000V
- High surge current capability
- Polarity: Color band denotes cathode

#### Applications

- Rectifier

#### Marking

- RS1X  
X : From A To M



#### Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	RS1						
				A	B	D	G	J	K	M
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	$V_{RMS}$	V		35	70	140	280	420	560	700
Maximum DC Blocking Voltage	$V_{DC}$	V		50	100	200	400	600	800	1000
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L$ (Fig.1)	1.0						
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave, 1 cycle, $T_a=25\text{ C}$	30						
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	°C		-55 ~ +150						

#### Electrical Characteristics (T=25°C Unless otherwise specified)

Item	Symbol	Unit	Test Condition	RS1						
				A	B	D	G	J	K	M
Peak Forward Voltage	$V_F$	V	$I_F=1.0A$	1.3						
Maximum reverse recovery time	$t_{rr}$	ns	$I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$	150			250		500	
Peak Reverse Current	$I_{RRM1}$	$\mu A$	$V_{RM}=V_{RRM}$	$T_j=25\text{ °C}$		5				
	$I_{RRM2}$			$T_j=125\text{ °C}$		50				
Thermal Resistance(Typical)	$R_{\theta J-A}$	°C/W	Between junction and ambient		55					
	$R_{\theta J-L}$		Between junction and terminal		25					

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

FIG.1: FORWARD CURRENT DERATING CURVE

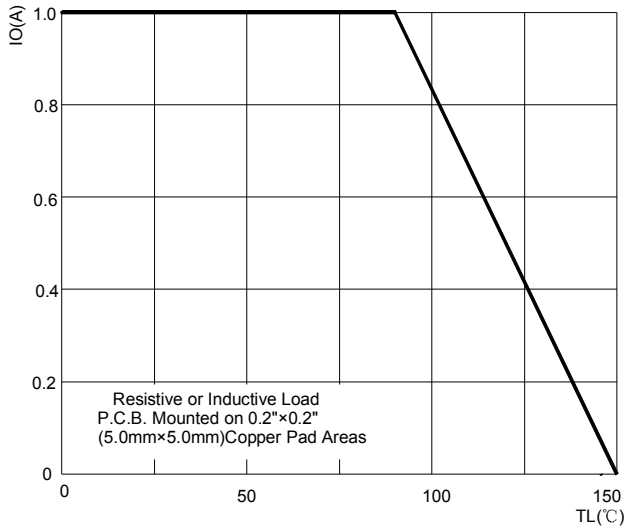


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

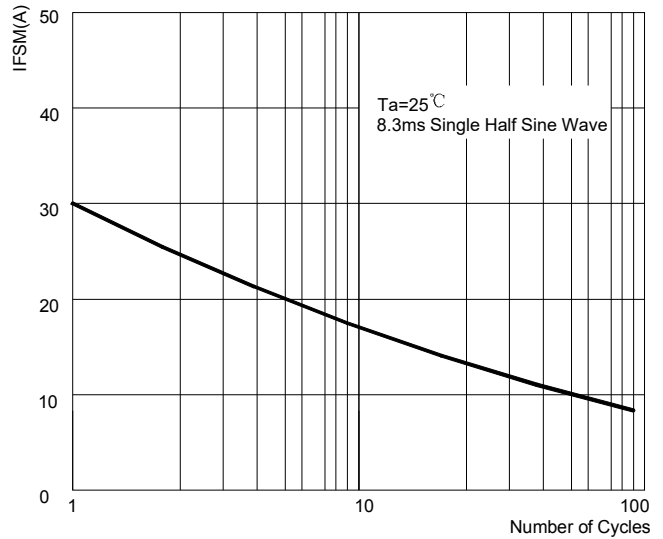


FIG.3: TYPICAL FORWARD CHARACTERISTICS

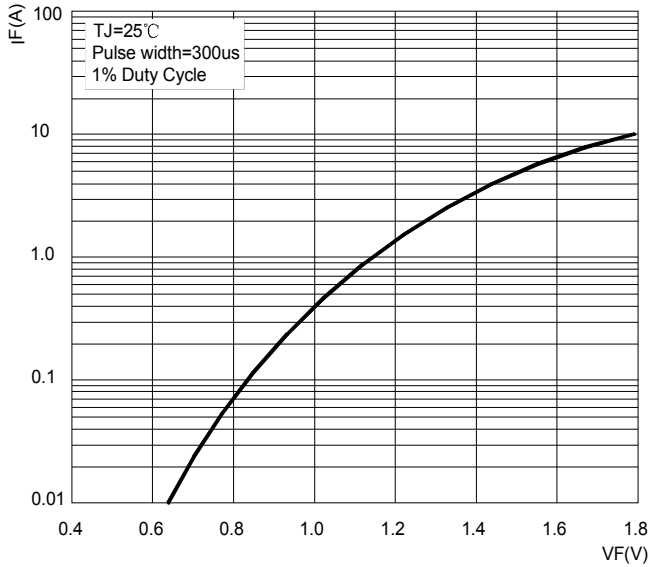


FIG.4: TYPICAL REVERSE CHARACTERISTICS

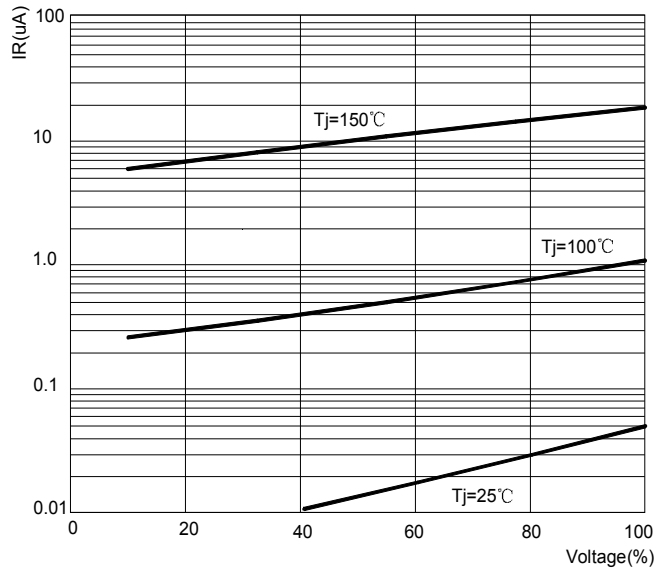
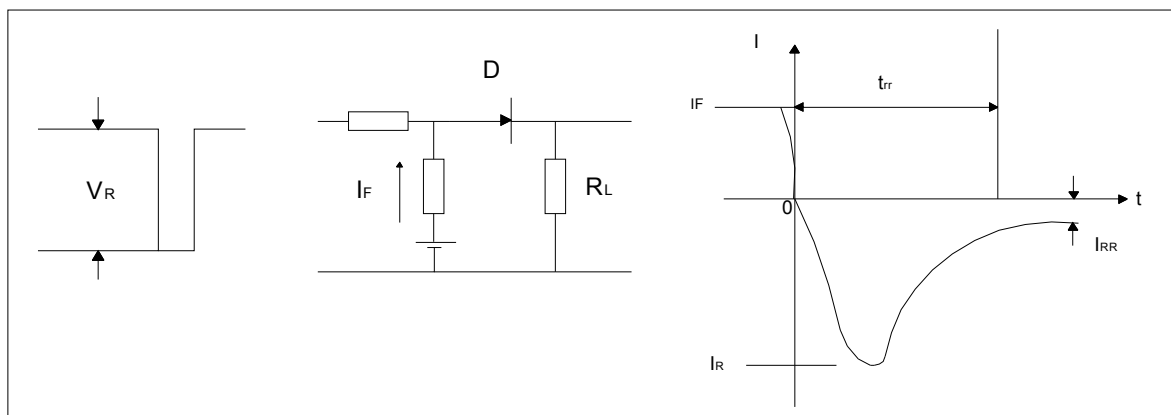
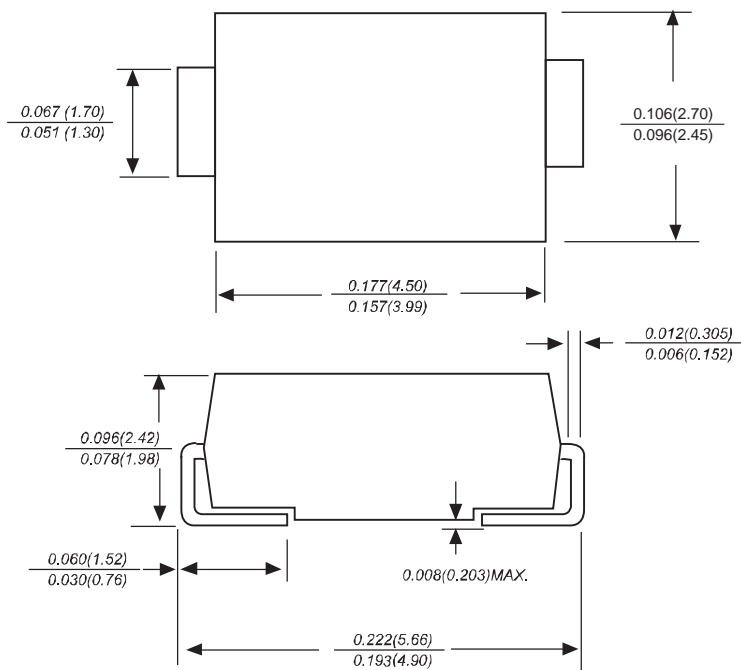


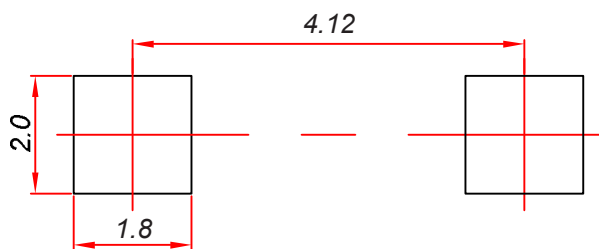
FIG.5: Diagram of circuit and Testing wave form of reverse recovery time





Dimensions in inches and (millimeters)

**SMAG Suggested Pad Layout**



- Note:**
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05$ mm.
  3. The pad layout is for reference purposes only.

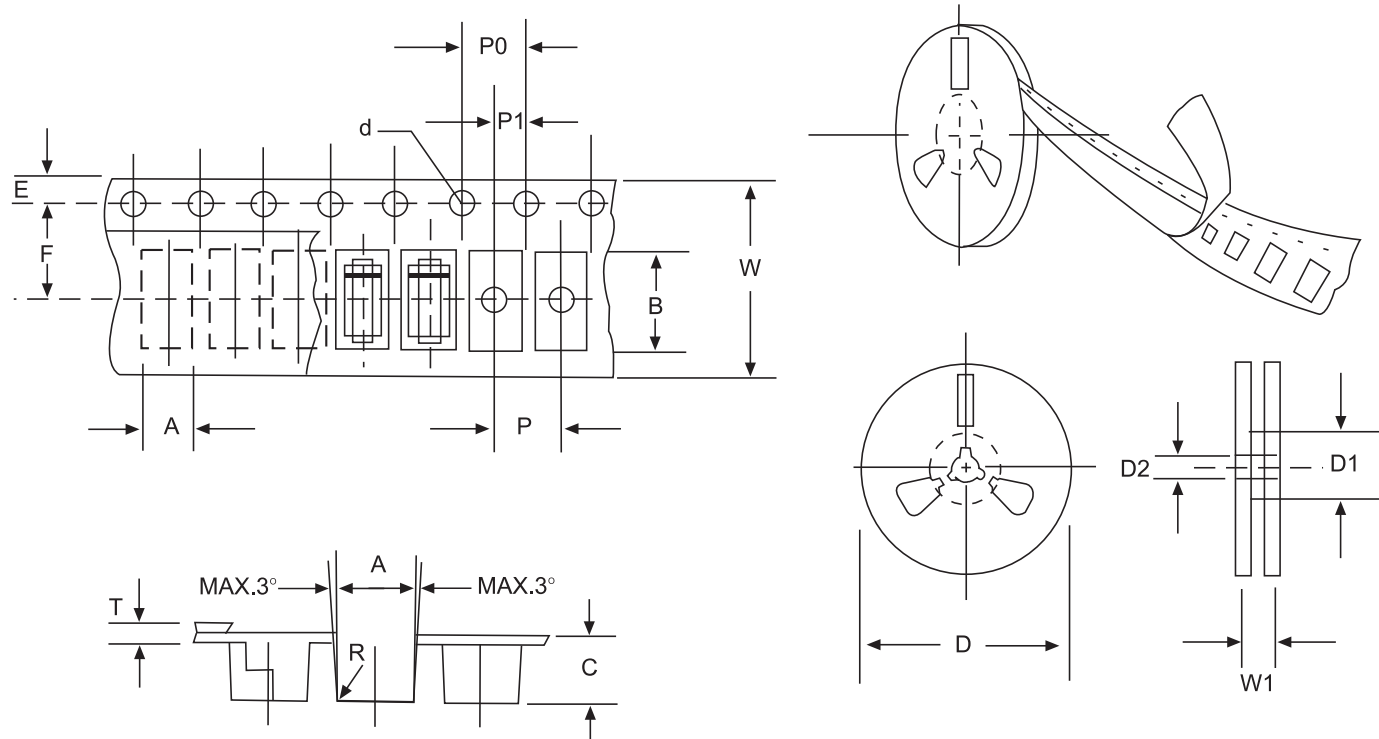


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 ( 2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.